L Number	Hits	Search Text	DB	Time stamp
1	42	(chip IC die) with (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 11:48
2	5	sasakura-takahiro.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 11:50
3	193	abe-seiichi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 11:59
4	36	(electronic adj component) with ((power adj circuit) (power adj supply adj module))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 12:00
5	441	257/777,784,723,676,684.ccls. and power and (heat adj (sink plate slug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:00
6	5552	(power adj supply) and (open$4 recess$4) and (heat adj (sink plate spreader element slug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:03
7	1998	(power adj supply) and (open$4 recess$4) and (heat adj (sink plate spreader element slug)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:03
9	153	(power adj supply) with (open$4 recess$4) and (heat adj (sink plate spreader element slug)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:05
10	28	257/737-738,675,706,711-713.ccls. and (power adj supply) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:13
11	1060	(power adj supply) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:17
12	9621	(chip IC die) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:18
13	2022	(chip IC die) with (heat adj (sink plate element slug spreader)) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:20
14	17	("4042539" | "4740425" | "4876588" | "4914551" | "5022968" | "5028984" | "5206792" | "5208103" | "5218215" | "5262674" | "5300158" | "5343073" | "5346765" | "5367196" | "5422788" | "5591034" | "5608267").PN.	USPAT	2003/08/14 14:23

15	12	("5397917" | "5583378" | "5724230" | "5726493" | "5796038" | "5854511" | "5866943" | "5886408" | "5909056" | "5926371" | "6020637" | "6046499").PN.	USPAT	2003/08/14 14:33
-	8	(("20030052393") or ("5625221") or ("6252299") or ("5394010")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:34
-	81750	(power adj supply) and (chip die IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:36
-	637	(power adj supply) and (chip die IC) and stack and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:39
-	337	(power adj supply and module) and (chip die IC) and stack and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:49
-	6	257/777,784,723,676,684.ccls. and (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 13:46
-	1	257/685-686,690-691.ccls. and (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:59
-	0	20030047800.URPN.	USPAT	2003/08/13 19:53
-	5	257/737-738,675,706,711-713.ccls. and (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 14:08
-	43	257/777,784,723,676,684.ccls. and (power adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:59
-	46	257/685-686,690-691.ccls. and (power adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:59
-	55	257/737-738,675,706,711-713.ccls. and (power adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/14 11:45